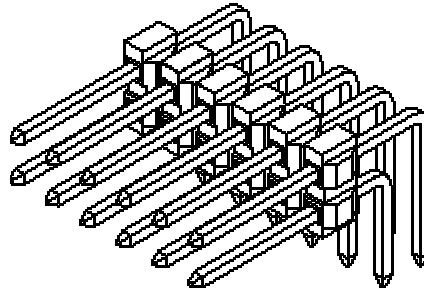




PRODUCT SPECIFICATION



SERIES 71764

C-GRID® RIGHT ANGLE THROUGH HOLE .100" GRID DUAL ROW LOW PROFILE HEADER WITH BREAK OFF OPTION SERIES 71764

- 1.0 SCOPE
- 2.0 PRODUCT DESCRIPTION
 - 2.1 PRODUCT NAME AND SERIES NUMBER
 - 2.2 DIMENSIONS, MATERIALS, PLATINGS AND MARKINGS
- 3.0 APPLICABLE DOCUMENTS AND SPECIFICATIONS
- 4.0 RATINGS
 - 4.1 VOLTAGE
 - 4.2 CURRENT
 - 4.3 TEMPERATURE
- 5.0 PERFORMANCE
 - 5.1 ELECTRICAL REQUIREMENTS
 - 5.2 MECHANICAL REQUIREMENTS
- 6.0 PACKAGING

REVISION: A	ECR/ECN INFORMATION: EC No: UCP2006-0528 DATE: 2005/09/12	TITLE: .100" GRID RIGHT ANGLE DUAL ROW LOW PROFILE BREAKAWAY HEADER	SHEET No. 1 of 2
DOCUMENT NUMBER: PS-71764	CREATED / REVISED BY: MIBARRA	CHECKED BY: BBARKER	APPROVED BY: SMILLER



PRODUCT SPECIFICATION

1.0 SCOPE

This specification covers the C-Grid® right angle low profile dual row header with break-off option. The wafer (header body) has a low profile and is designed to be easily modified to a smaller circuit size in the field if required. The mating pins are .025in (0.64mm) square and have .100in (2.54mm) grid spacing. The solder tails are rounded to enhance registration to the circuit board during assembly.

2.0 PRODUCT DESCRIPTION

2.1 PRODUCT NAME AND SERIES NUMBER

SERIES 71764: C-Grid® Right Angle .100" Grid Dual Row Low Profile Header

2.2 DIMENSIONS, MATERIALS, PLATINGS AND MARKINGS

The product is available in circuit sizes of 4 through 80 circuits and is end to end stackable when supplied in discrete circuit size by Molex manufacturing. Product can also be ordered with selective voids. The wafer is produced from High Temperature Thermal Plastic – Liquid Crystal Polymer (LCP) having a UL 94V-0 flammability rating. Mating pin lengths are .240in (6.0mm), and .320in (8.1mm) with Gold or tin plating. Tail length options are .110in (2.8mm). For further details, please refer to the sales documents in section 3.0.

3.0 APPLICABLE DOCUMENTS AND SPECIFICATIONS

<u>MOLEX DOCUMENT</u>	<u>DESCRIPTION</u>
SDA-71764-****	SALES DRAWING, RIGHT ANGLE DUAL ROW
PK-70873-0353	PACKAGING SPECIFICATION, CIRCUIT SIZES 4-8
PK-70873-0075	PACKAGING SPECIFICATION, CIRCUIT SIZES 10-80

4.0 RATINGS

4.1 **VOLTAGE:** 250 Volts D.C.

4.2 **CURRENT:** 2.5 Amp D.C. max.

4.3 **TEMPERATURE:**

4.3.1 **PROCESSING TEMPERATURE:** Product is suitable for wave soldering and is I.R. reflow compatible.

4.3.2 **OPERATING TEMPERATURE:** -40°C to 120°C

5.0 PERFORMANCE

5.1 ELECTRICAL REQUIREMENTS

5.1.1 **INSULATION RESISTANCE:** Greater than 1000MΩ.

5.1.2 **DIELECTRIC WITHSTANDING VOLTAGE:** Greater than 600 Volts at sea level.

5.2 MECHANICAL REQUIREMENTS

Header pin retention (push out force): 4 lbs min before soldering.

6.0 PACKAGING

Refer to section 3.0 for packaging documents.

<u>REVISION:</u> A	<u>EGR/ECN INFORMATION:</u> EC No: UCP2006-0528 DATE: 2005/09/12	<u>TITLE:</u> .100" GRID RIGHT ANGLE DUAL ROW LOW PROFILE BREAKAWAY HEADER	<u>SHEET No.</u> 2 of 2
<u>DOCUMENT NUMBER:</u> PS-71764	<u>CREATED / REVISED BY:</u> MIBARRA	<u>CHECKED BY:</u> BBARKER	<u>APPROVED BY:</u> SMILLER